



Material Content Data Sheet



Sales Product Name				BSC014N04LSI		Issued		20. July 2018	
MA#				MA001073322					
Package				PG-TDSON-8-17		Weight*		118.55 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.009	0.85	0.85	8515	8515	
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		319		
	inorganic material	phosphorus	7723-14-0	0.011	0.01		96		
	non noble metal	copper	7440-50-8	37.762	31.86	31.90	318539	318954	
wire	noble metal	gold	7440-57-5	0.045	0.04	0.04	376	376	
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		731		
	plastics	epoxy resin	-	6.156	5.19		51933		
	inorganic material	silicondioxide	60676-86-0	37.112	31.31	36.57	313058	365722	
leadfinish	non noble metal	tin	7440-31-5	1.470	1.24	1.24	12399	12399	
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1396	1396	
solder	noble metal	silver	7440-22-4	0.036	0.03		306		
	non noble metal	tin	7440-31-5	0.029	0.02		245		
	non noble metal	lead	7439-92-1	1.387	1.17	1.22	11699	12250	
heatspreader	inorganic material	phosphorus	7723-14-0	0.003	0.00		28		
	non noble metal	zinc	7440-66-6	0.013	0.01		113		
	non noble metal	iron	7439-89-6	0.269	0.23		2266		
	non noble metal	copper	7440-50-8	10.909	9.20	9.44	92024	94431	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.007	0.01		56		
	non noble metal	zinc	7440-66-6	0.026	0.02		223		
	non noble metal	iron	7439-89-6	0.529	0.45		4463		
	non noble metal	copper	7440-50-8	21.482	18.12	18.60	181215	185957	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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